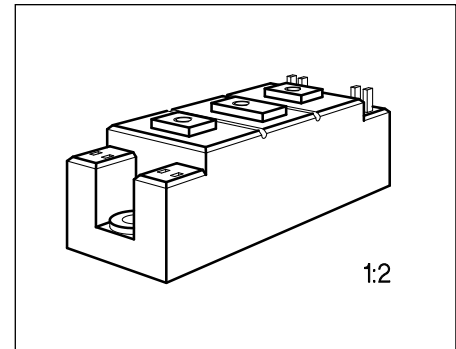


## SIMOPAC® Module

## BSM 214 A

$V_{DS} = 100 \text{ V}$   
 $I_D = 2 \times 125 \text{ A}$   
 $R_{DS(on)} = 0.013 \text{ } \Omega$

- Power module
- Half-bridge
- N channel
- Enhancement mode
- Package with insulated metal base plate
- Package outline/Circuit diagram: 2a<sup>1)</sup>



| Type      | Ordering Code   |
|-----------|-----------------|
| BSM 214 A | C67076-S1100-A2 |

### Maximum Ratings

| Parameter  | Symbol               | Values         | Unit             |
|--|----------------------|----------------|------------------|
| Drain-source voltage   | $V_{DS}$             | 100            | V                |
| Drain-gate voltage, $R_{GS} = 20 \text{ k}\Omega$            | $V_{DGR}$            | 100            |                  |
| Gate-source voltage  | $V_{GS}$             | $\pm 20$       |                  |
| Continuous drain current, $T_C = 25 \text{ }^\circ\text{C}$  | $I_D$                | 125            | A                |
| Pulsed drain current, $T_C = 25 \text{ }^\circ\text{C}$      | $I_{D \text{ puls}}$ | 375            |                  |
| Operating and storage temperature range                      | $T_j, T_{stg}$       | - 55 ... + 150 | $^\circ\text{C}$ |
| Power dissipation, $T_C = 25 \text{ }^\circ\text{C}$         | $P_{tot}$            | 400            | W                |
| Thermal resistance<br>Chip-case                              | $R_{th \text{ JC}}$  | $\leq 0.31$    | K/W              |
| Insulation test voltage <sup>2)</sup> , $t = 1 \text{ min.}$ | $V_{is}$             | 2500           | $V_{ac}$         |
| Creepage distance, drain-source                              | –                    | 16             | mm               |
| Clearance, drain-source                                      | –                    | 11             |                  |
| DIN humidity category, DIN 40 040                            | –                    | F              | –                |
| IEC climatic category, DIN IEC 68-1                          | –                    | 55/150/56      |                  |

1) See chapter Package Outline and Circuit Diagrams.

2) Insulation test voltage between drain and base plate referred to standard climate 23/50 in acc. with DIN 50 014, IEC 146, para. 492.1.

## Electrical Characteristics

at  $T_j = 25\text{ °C}$ , unless otherwise specified.

| Parameter | Symbol | Values |      |      | Unit |
|-----------|--------|--------|------|------|------|
|           |        | min.   | typ. | max. |      |

## Static Characteristics

|  |               |        |           |             |               |
|--|---------------|--------|-----------|-------------|---------------|
| Drain-source breakdown voltage<br>$V_{GS} = 0, I_D = 0.25\text{ mA}$   | $V_{(BR)DSS}$ | 100    | –         | –           | V             |
| Gate threshold voltage<br>$V_{GS} = V_{DS}, I_D = 1\text{ mA}$   | $V_{GS(th)}$  | 2.1    | 3.0       | 4.0         |               |
| Zero gate voltage drain current<br>$V_{DS} = 50\text{ V}, V_{GS} = 0$<br>$T_j = 25\text{ °C}$<br>$T_j = 125\text{ °C}$ | $I_{DSS}$     | –<br>– | 50<br>300 | 250<br>1000 | $\mu\text{A}$ |
| Gate-source leakage current<br>$V_{GS} = 20\text{ V}, V_{DS} = 0$  | $I_{GSS}$     | –      | 10        | 100         | nA            |
| Drain-source on-state resistance<br>$V_{GS} = 10\text{ V}, I_D = 38\text{ A}$  | $R_{DS(on)}$  | –      | 0.01      | 0.013       | $\Omega$      |

## Dynamic Characteristics

|   |              |    |     |     |    |
|---|--------------|----|-----|-----|----|
| Forward transconductance<br>$V_{DS} \geq 2 \times I_D \times R_{DS(on)max.}, I_D = 38\text{ A}$   | $g_{fs}$     | 40 | 60  | –   | S  |
| Input capacitance<br>$V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$   | $C_{iss}$    | –  | 9   | 12  | nF |
| Output capacitance<br>$V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$  | $C_{oss}$    | –  | 4   | 6   |    |
| Reverse transfer capacitance<br>$V_{GS} = 0, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$  | $C_{rss}$    | –  | 1.6 | 2.4 |    |
| Turn-on time $t_{on}$ ( $t_{on} = t_{d(on)} + t_r$ )<br>$V_{CC} = 50\text{ V}, V_{GS} = 10\text{ V}$<br>$I_D = 78\text{ A}, R_{GS} = 3.3\ \Omega$     | $t_{d(on)}$  | –  | 50  | –   | ns |
|   | $t_r$        | –  | 190 | –   |    |
| Turn-off time $t_{off}$ ( $t_{off} = t_{d(off)} + t_f$ )<br>$V_{CC} = 50\text{ V}, V_{GS} = 10\text{ V}$<br>$I_D = 78\text{ A}, R_{GS} = 3.3\ \Omega$ | $t_{d(off)}$ | –  | 190 | –   |    |
|   | $t_f$        | –  | 50  | –   |    |

## Electrical Characteristics (cont'd)

at  $T_j = 25\text{ °C}$ , unless otherwise specified.

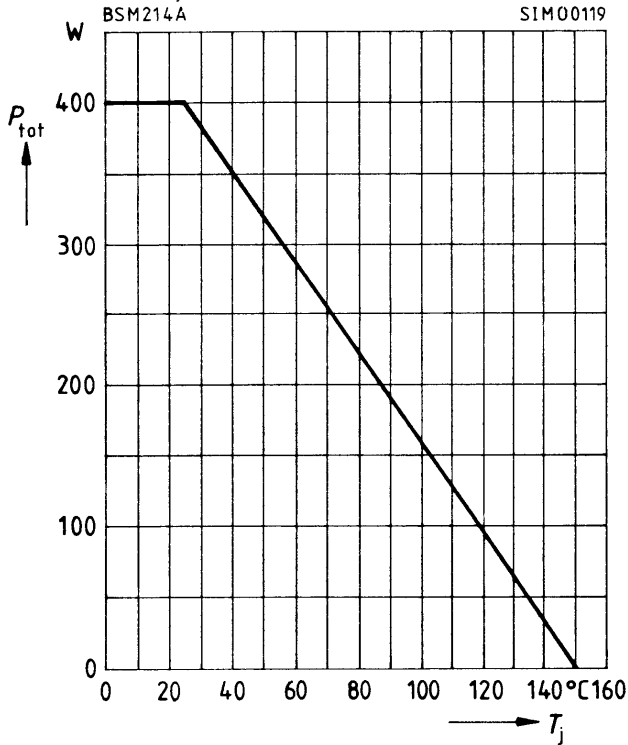
| Parameter | Symbol | Values |      |      | Unit |
|-----------|--------|--------|------|------|------|
|           |        | min.   | typ. | max. |      |

### Reverse diode

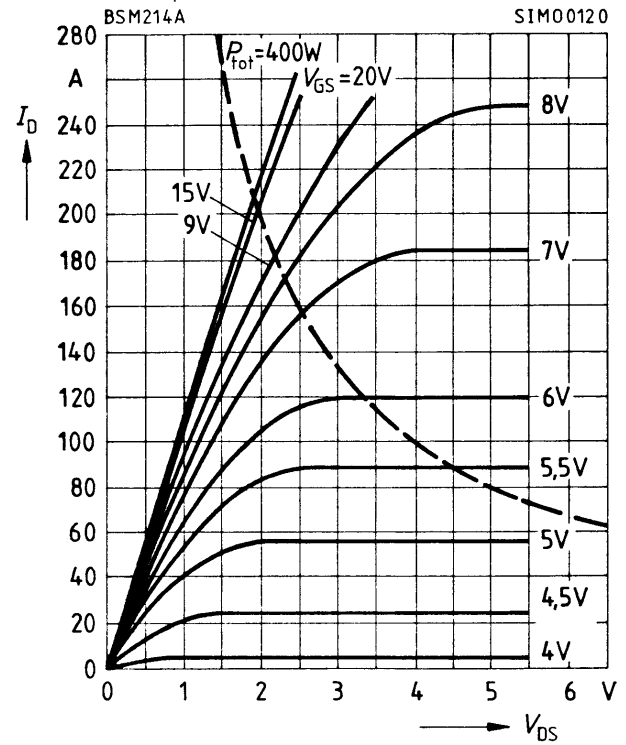
|   |          |   |      |     |               |
|---|----------|---|------|-----|---------------|
| Continuous reverse drain current<br>$T_C = 25\text{ °C}$  | $I_S$    | – | –    | 125 | A             |
| Pulsed reverse drain current<br>$T_C = 25\text{ °C}$  | $I_{SM}$ | – | –    | 375 |               |
| Diode forward on-voltage<br>$I_F = 250\text{ A}$ , $V_{GS} = 0$                                     | $V_{SD}$ | – | 1.25 | 1.6 | V             |
| Reverse recovery time<br>$I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$   | $t_{rr}$ | – | 320  | –   | ns            |
| Reverse recovery charge<br>$I_F = I_S$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$ | $Q_{rr}$ | – | 3.6  | –   | $\mu\text{C}$ |

Characteristics at  $T_j = 25^\circ\text{C}$ , unless otherwise specified.

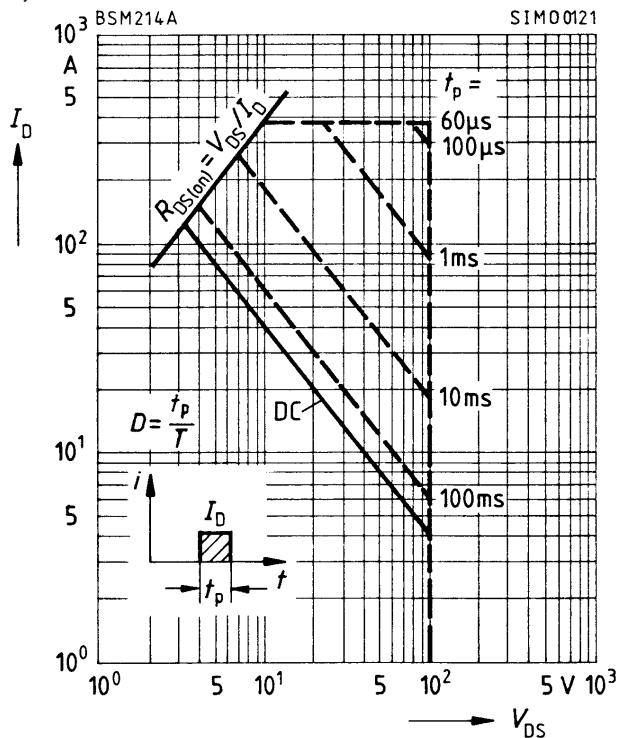
**Power dissipation**  $P_{\text{tot}} = f(T_C)$   
parameter:  $T_j = 150^\circ\text{C}$



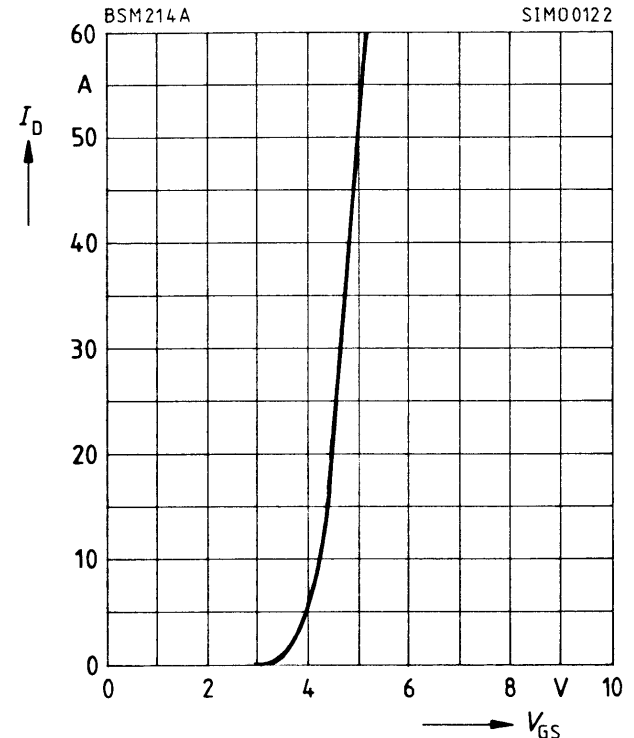
**Typ. output characteristics**  $I_D = f(V_{\text{DS}})$   
parameter:  $t_p = 80 \mu\text{s}$



**Safe operating area**  $I_D = f(V_{\text{DS}})$   
parameter: single pulse,  $T_C = 25^\circ\text{C}$   
 $T_j \leq 150^\circ\text{C}$

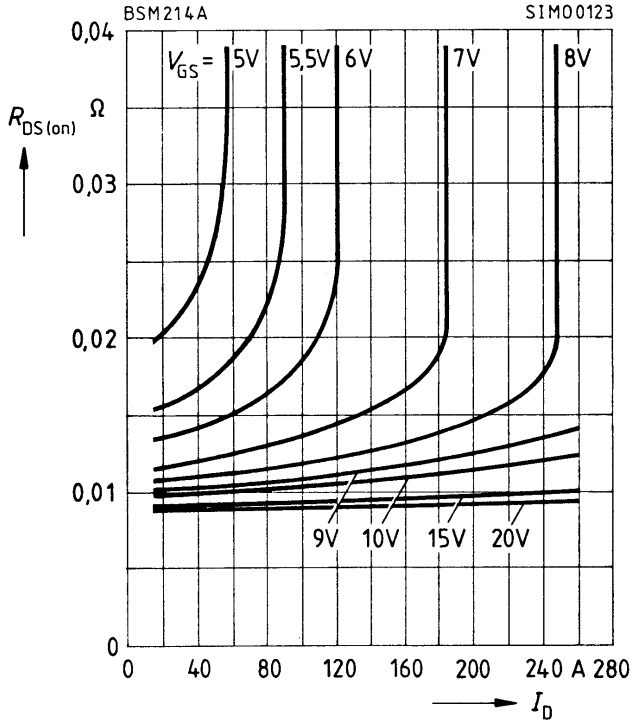


**Typ. transfer characteristic**  $I_D = f(V_{\text{GS}})$   
parameter:  $t_p = 80 \mu\text{s}$ ,  $V_{\text{DS}} = 25 \text{ V}$



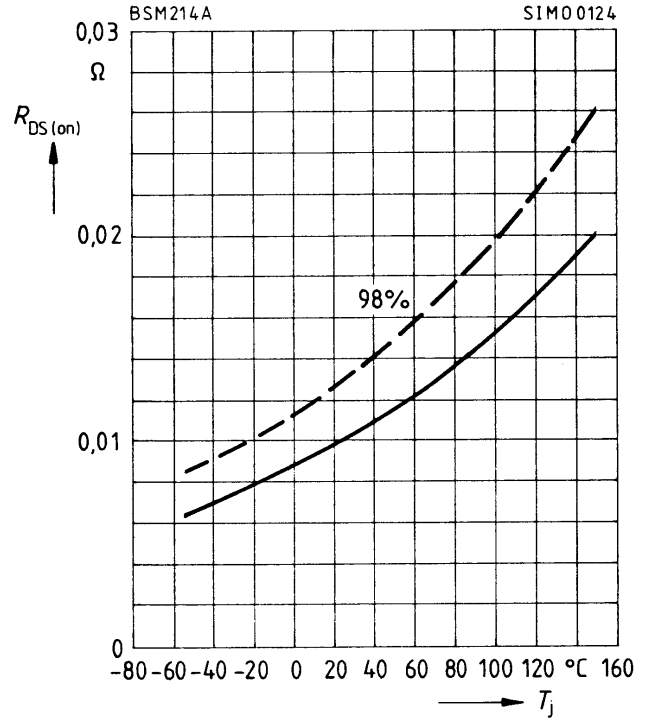
**Typ. on-state resistance**

$R_{DS(on)} = f(I_D)$   
parameter:  $V_{GS}$



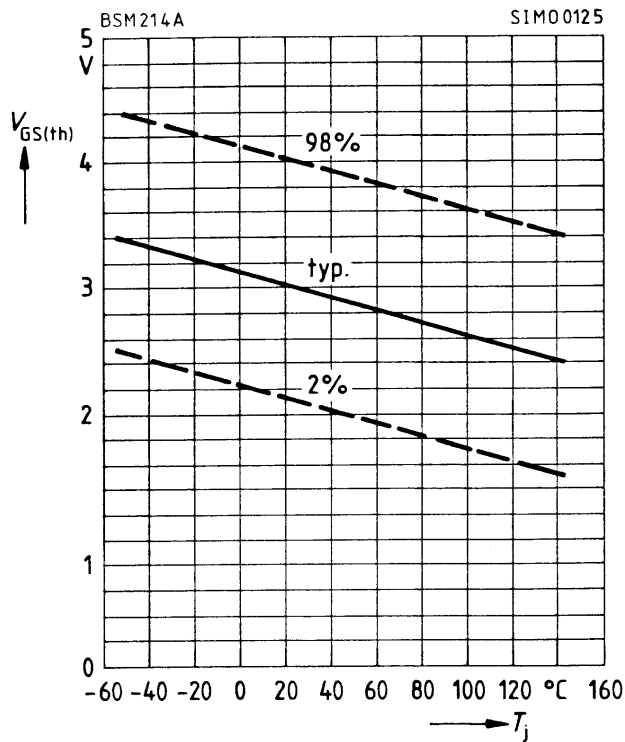
**On-state resistance  $R_{DS(on)} = f(T_j)$**

parameter:  $I_D = 38$  A;  $V_{GS} = 10$  V (spread)



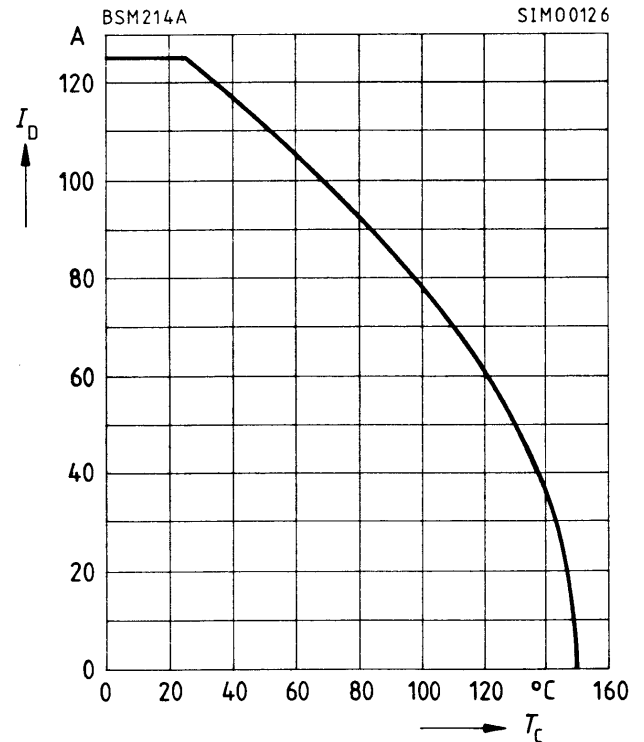
**Gate threshold voltage  $V_{GS(th)} = f(T_j)$**

parameter:  $V_{DS} = V_{GS}$ ,  $I_D = 1$  mA (spread)



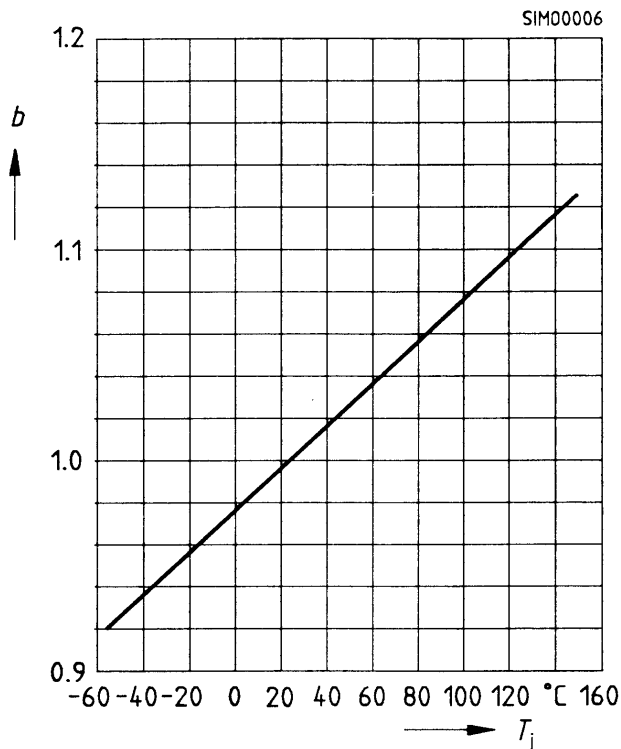
**Drain current  $I_D = f(T_c)$**

parameter:  $V_{GS} \geq 10$  V,  $T_j = 150$   $^{\circ}C$



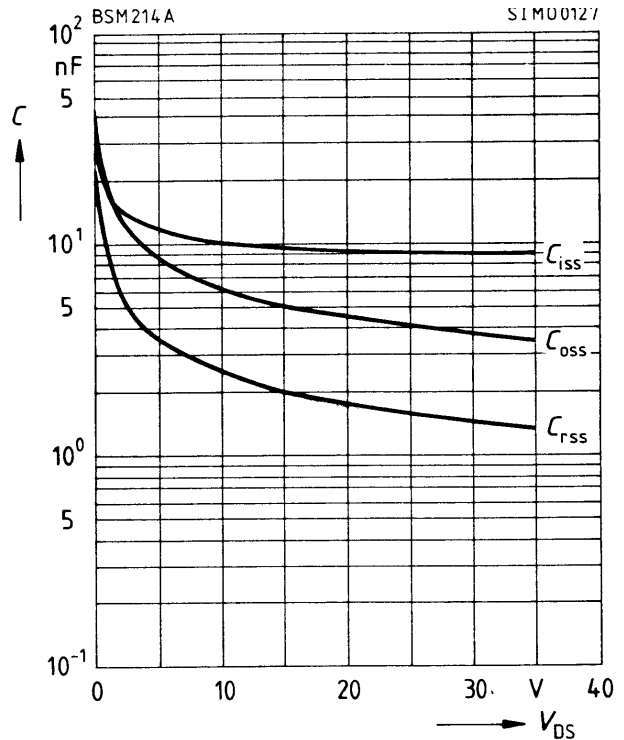
### Drain source breakdown voltage

$$V_{(BR)DSS}(T_j) = b \times V_{(BR)DSS}(25^\circ\text{C})$$



### Typ. capacitances $C = f(V_{DS})$

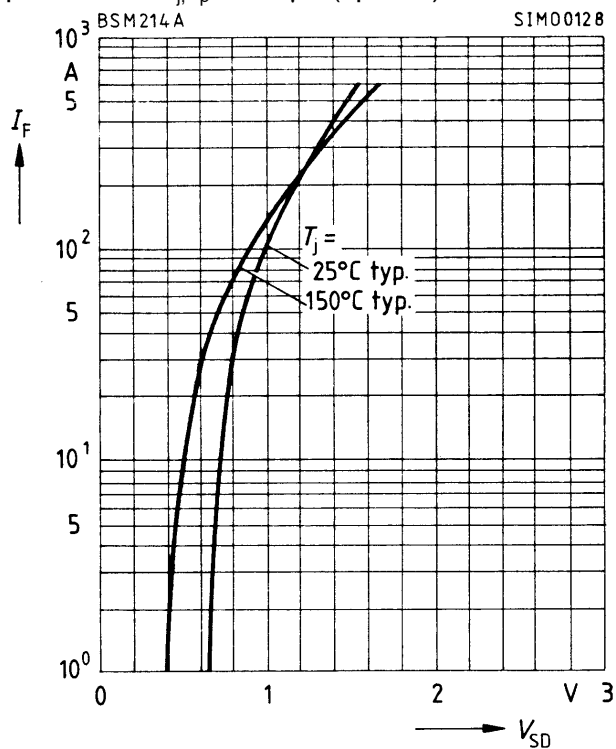
parameter:  $V_{GS} = 0, f = 1 \text{ MHz}$  (spread)



### Forward characteristics

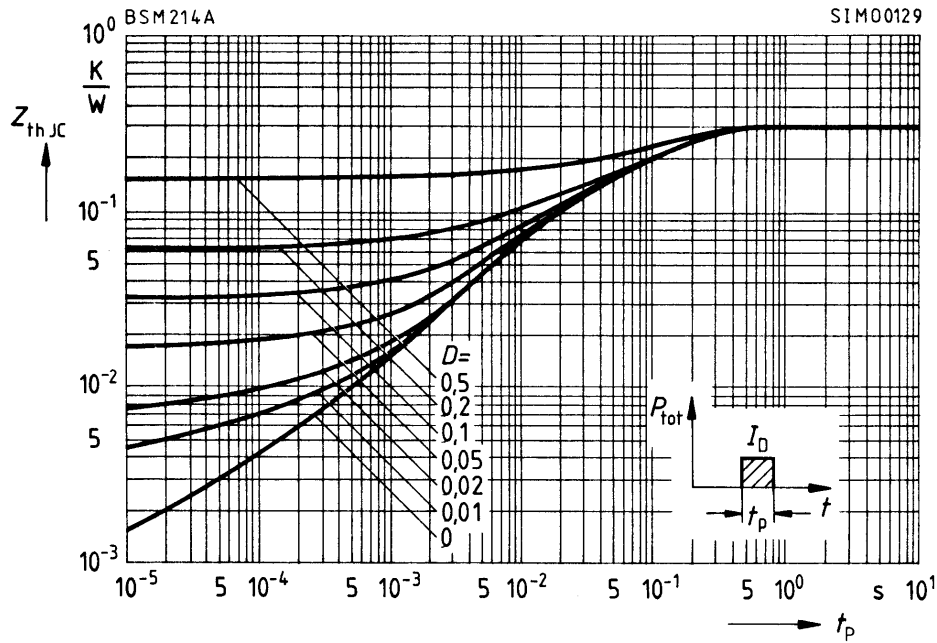
of reverse diode  $I_F = f(V_{SD})$

parameter:  $T_j, t_p = 80 \mu\text{s}$  (spread)



### Transient thermal impedance $Z_{thJC} = f(t_p)$

parameter:  $D = t_p/T$



### Typ. gate charge $V_{GS} = f(Q_{Gate})$

parameter:  $I_{Dpuls} = 185$  A

